	CONNECTING CS INDUSTRIES® International and Pan	PC, Bannockb	urn, Illinois. A	All rights reserved u ntions.	nder both	This docume level parts, t	ent is a declarat he declaration e	on of the subs ncompasses al	tances within t l lower level r	he manufactur naterials for wl	er listed iter hich the ma	n. Note: if nufacturer	f the item is an as has engineering	sembly with lower responsibility.
1752-21.1	IPC Web Site for Information on IPC-1752 Standard http://www.ipc.org/IPC-175x				Form Type Distribute	orm Type * Declaration Class * Class 6 - RoHS Yes/No, Homogeneous M			eneous Materia	erials and Mfg Information				
Supplie	r Information													
Company	name*	Company unique ID			1	Unique ID Authority				Response Date*				
onsemi											2024-05-16			
Contact N	lame	Title - Contact			]	Phone - Contact*				Email - Contact*				
Product-l	Env-Stewards	Product Enviro Compliance				NA				Product-Env-Stewards@onsemi.com				
uthorize	ed Representative*	Title - Representative			]	Phone - Representative*				Email - Representative*				
Product-l	Env-Stewards	Product Enviro Compliance				NA				Product-Env-Stewards@onsemi.com				
	Requester Item Number Mfr Item   TIP32AG		Number Mfr Item Name				Effective Date	e Version Manufacturing Site		W	eight*	UOM	Unit Type	
			ĩ	BIP T0220 PNP 3A 60V			2024-05-16 CN5			19	62.01	mg	Each	
/Ianufa	cturing Proccess Informat	tion						-						
	Terminal Plating / Grid Array Material		Ferminal Base Alloy J-STD-020 I		-STD-020 MS	L Rating	Peak Process Body Temperat		perature Max	ture Max Time at Peak Tempe		e Numb	er of Reflow Cyc	les
Matte Tin (Sn) - annealed		CU Alloy NA			0 C		30		seconds	3				
omments	3													
or more	information regarding material	composition	please refer to	page 3										

RoHS Material Composition Declar	ation			Declaration Type *	Detailed
Directive 2015/863/EU amending Rol Directive 2011/65/EU	(Pb), Mercury (Hg), Hexav		ninated Biphenyls (PBB), Polybror	dmium and quantity limit of 0.1% by mass (100 ninated Diphenyl Ethers (PBDE), and Bis(2-eth	
cadmium, hexavalentchromium, polyb contains a RoHS restricted substance i encompass all such components.Suppl as of the date that Supplier completes Company acknowledges that Supplier independently verified information pro- certification in this paragraph.If the Co	rominated biphenyls and/or polybror nexcess of an applicable quantity lim ier certifies that it gathered the inforr this form.Supplier acknowledges that may have relied on informationprovi ovided by others, Supplier agrees that ompany and the Supplier enter into a clusivesource of the Supplier's liabili	ninated diphenyl ethers (each a "R it, please indicate below which, if nation it provides in this form usin Company will rely on this certifud ded by others in completing this f , at a minimum, itssuppliers have written agreement with respect to ty and the Company's remedies for	toHS restricted substance") in exce any, RoHS exemption you believe ag appropriate methods to ensure it cation in determining the complian orm, and that Supplier may not hav provided certifications regarding th the identified part,the terms and co or issues that arise regarding inform	ropean Union member states) of the part identifies so of the applicable quantity limit identified about may apply. If the part is an assembly with lows a accuracy and that such information is true and ce of its products with European Union member re independently verified such information. How heir contributions to the part, and those certifica motions of that agreement, including any warra nation the Supplier provides in this form. In the	ove. If a homogeneous material within the part er level components, the declaration shall l correct to the best of its knowledge and belief, r state laws that implement the RoHS Directive. wever, in situations where Supplier has not tions are at least as comprehensive as the inty rights and/or remedies provided as part of
<b>RoHS Declaration *</b> 4	- Item(s) does not contain RoHS restr	icted substances per the definition	above except for selected exempti	ons Supplier Acceptance	* Accepted
Exemption: 7a: Lead in high meltin Exemption: 7c-I Electrical and elect	g temperature type solders (i.e. lead ronic components containing lead i	l based solder alloys containing n a glass or ceramic other than	85% by weight or more lead). dielectric ceramic in capacitors, o	e.g. piezoelectronic devices, or in a glass or ce	eramic matrix compound.
Exemption List Version	EL-2011/534/EU				
Declaration Signature					
Instructions: Complete all of the rec Requester) and click on Submit For			Supplier Acceptance drop-down	. This will display the signature area. Digital	ly sign the declaration (if required by the
Supplier Digital Signature	Rastislav Drska	Le			

## Homogeneous Material Composition Declaration for Electronic Products

SubItem Instructions: The presence of any JIG Level A or B substances must be declared. [1] indicate the subpart in which the substance is located, [2] provide a description of the homogeneous material [3], enter the weight of the homogeneous material.

Homogeneous Material	Weight	Unit of Measure	Level	Substance	CAS	Exempt	Weight	Unit of Measure
Die	3.55	mg	Supplier	Silicon (Si)	7440-21-3		3.5145	mg
			Supplier	Lead Bisilicate	65997-18-4	7c	0.0355	mg
Die Attach	82.98	mg	А	Lead (Pb)	7439-92-1	7a	78.831	mg
			Supplier	Tin (Sn)	7440-31-5		4.149	mg
Lead Frame	1300.04	mg	Supplier	Copper (Cu)	7440-50-8		1300.04	mg
Mold Compound-Black	543.9	mg		Brominated epoxy resin	proprietary data		10.878	mg
			Supplier	Phenolic Resin	Proprietary Data		27.195	mg
			В	Antimony Trioxide (Sb2O3)	1309-64-4		16.317	mg
			Supplier	Fused Silica (SiO2)	60676-86-0		435.12	mg
			Supplier	Ortho-Cresol Novolac Resin	29690-82-2		54.39	mg
Plating	31.13	mg	Supplier	Tin (Sn)	7440-31-5		31.13	mg
Wire Bond - Al	0.41	mg	Supplier	Aluminum (Al)	7429-90-5		0.41	mg